



**EECS 143
Microfabrication
Technology**

Department of Electrical Engineering and
Computer Sciences
University of California, Berkeley

Week #3 Quiz--Active Area Definition

Name _____ Section ____ Date _____

- (1) How does spin speed and time affect photoresist application?
- (2) What is the purpose of the soft bake (before exposure)?
- (3) What color are the lights in the lithography room, and why?
- (4) What chemical do we use to define the features in the photoresist?
- (5) What chemical do we use to define the features in the oxide layer?
- (6) What chemical do we use to remove the photoresist after we're all done?
- (7) Will the dark areas on the mask produce islands of oxide or pits in the surrounding oxide?
- (8) What might happen if we do not leave the wafers in the oxide etchant long enough?
- (9) Where do we keep the ointment to treat HF burns?
- (10) What is the purpose of HMDS?

A. Franke 8/31/99